



PRESS RELEASE

August 2023

IMAPS 56th International Symposium on Microelectronics Planned for October 2-5, 2023 in San Diego, California

The 56th International Symposium on Microelectronics (IMAPS 2023) will be held October 2-5, 2023, at the Town & Country Resort in San Diego, California. This jam-packed, annual conference brings together industry engineers, researchers and top experts involved in advanced packaging and microelectronics assembly. IMAPS Symposium offers one of the most robust technical programs for microelectronics and advanced packaging technical content. Given the strength of the program, many participants engage with this event over many years, and each year the event welcomes hundreds of new/first-time visitors as well – early career packaging professionals, those new to the industry, as well as students.

The technical content will include a concurrent 5-track program with over 100 speakers and poster presentations covering topics related SiP/Design/Manufacturing Optimization; Wafer Level/Panel Level (Advanced RDL); High Performance/High Reliability; Advanced Package (Flip Chip, 2.5D, 3D, Optical); Advanced Process & Materials (Enabling Technologies).

Attendees can also register for up to four of our 16 Two-hour Professional Development Courses which provide a learning opportunity to enhance skills and grow career capabilities. This year's PDC topics include: Chiplet Design & Heterogeneous Integration; Fan-Out Wafer Level Packaging; Flip Chip Package; System-in-Package; Additive Manufacturing; 3D Package Assembly; RF & Heterogeneous Integration; Wire Bond; and more.

The program will include captivating keynotes (IBM Research, ASE, TSMC and Qorvo), panel sessions with interactive discussion, and numerous networking events. An exhibit hall will feature more than 90 booths showcasing product and service offerings of the current technologies and applications. Several networking events will be held on the show floor.

This year's General Chair, Suresh Jayaraman with Amkor Technology, said, "I am really thrilled to invite all industry colleagues and peers to IMAP2023 in San Diego where our theme is using chiplets to interconnect future devices. We have an exciting line up of PDCs, keynotes and technical sessions- not to mention unlimited opportunities to network and learn from each other. Hope to you see you all in San Diego."

In 2022, 865 people participated in the Symposium in Boston, including a good showing of members from overseas. The exhibitor hall was consistently busy with 93, 10x10 booths, all networking events were a great success, and tours at local university facilities were filled to capacity.

Conference details and registration are available at www.IMAPS2023.org

About IMAPS

The International Microelectronics Assembly and Packaging Society is the largest society dedicated to the advancement and growth of microelectronics and electronics packaging. Worldwide, IMAPS offers educational and marketing opportunities for industry professionals, packaging organizations, and students through technical conferences and workshops, professional development courses, IMAPSource microelectronics packaging research library, local chapters and exhibitions. The Society encompasses a wide-range of technologies and topics critical to microelectronics assembly and packaging, including: on-shoring, heterogenous integration, fan-out wafer level packaging, 2.5D/3D technologies, system-in-package, photonics/optical, power packaging, CPI, package design/modeling, interconnects, wire bonding, flip chip, MEMS, sensors, packaging for 5g/6g, RF/wireless, signal/power integrity, advanced materials, substrates and more.

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